

CHO-BOND® 1075

ONE COMPONENT CORROSION RESISTANT ELECTRICALLY CONDUCTIVE SILICONE SEALANT



Customer Value Proposition:

CHO-BOND 1075 is a silver plated aluminum filled, one-component conductive silicone designed for use as a fillet, gap filler and seam sealant on electrical enclosures for EMI shielding or electrical grounding. Minimum recommended bond line for CHO-BOND 1075 is 0.010 inches (0.25mm). In addition, CHO-BOND 1075 may be used for EMI gasket repair, bonding, and attachment in applications where moderate strength (100 psi) is required. The silver aluminum filler of CHO-BOND 1075 provides excellent galvanic corrosion resistance when applied to aluminum substrates. No volatile organic compounds (VOCs) and minimal shrinkage upon curing make CHO-BOND 1075 a good choice for a variety of commercial and military applications. CHO-BOND 1075's moisture cure silicone polymer system allows it to cure to the touch in 24 hours and provides a robust conductive and environmental seal over a wide range of application temperatures.

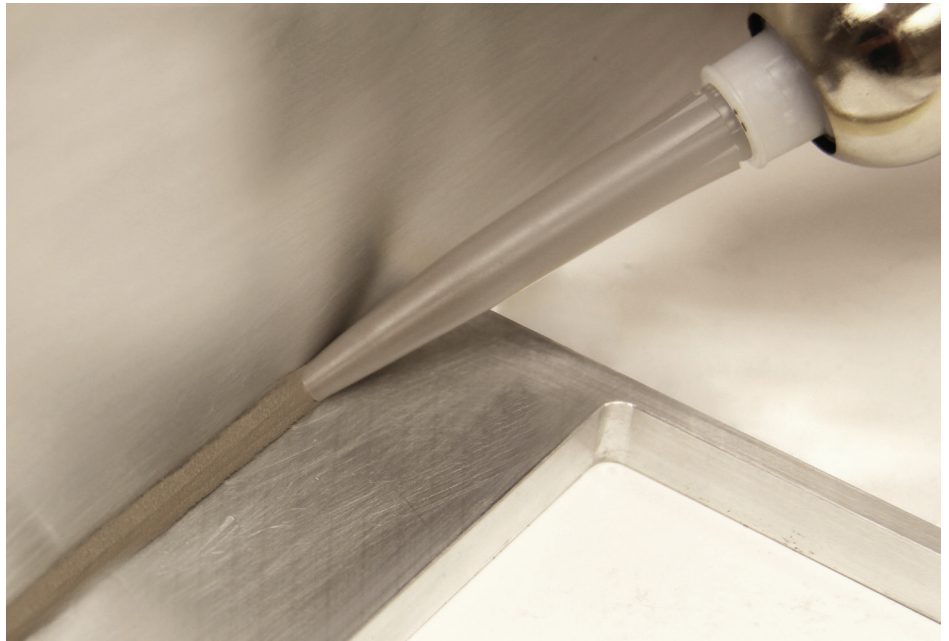
For best adhesion results, CHO-BOND 1075 should be used in conjunction with CHO-SHIELD 1086 primer. Typical applications include man portable electronics, radar and communication systems, EMI vents, military ground vehicles, and shelters.

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Features and Benefits:

- One component
- Silver plated aluminum filler
- No VOCs
- Moisture cure silicone
- Light weight
- Non corrosive cure mechanism
- Dry medium paste
- Easy to use, no weighing or mixing required.
- Excellent conductivity 0.010 ohm-cm outstanding galvanic corrosion resistance against aluminum substrates.
- Minimal shrinkage.
- 15 minute working life, rapid skin formation, 24 hr handling time, requires no pressure during curing, wide range of application temperatures. 1 week for full cure.
- More coverage per gram of material, minimal weight added to assembly or vehicle.
- No corrosive by-products generated during curing to damage substrate.
- Can be used on overhead or vertical surfaces.



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CHO-BOND 1075 - Product Information

Table 1 Typical Properties

CHO-BOND 1075		
Typical Properties	Typical Values	Test Method
Polymer	Silicone	N/A
Filler	Silver-Plated Aluminum	N/A
Mix Ratio, A : B (by weight)	1-part	N/A
Color	Gray	N/A (Q)
Consistency	Dry Medium Paste	N/A (Q)
Maximum DC Volume Resistivity	0.010 ohm-cm	CHO-95-40-5555* (Q/C)
Minimum Lap Shear Strength**	100 psi (689 kPa)	CHO-95-40-5300* (Q/C)
Minimum Peel Strength**	4.0 lb./inch (700 N/m)	CHO-95-40-5302* (Q/C)
Specific Gravity	2.0	ASTM D792 (Q/C)
Hardness	81 Shore A	ASTM-D2240 (Q/C)
Continuous Use Temperature	- 55°C to 200°C (-67 °F to 392 °F)	N/A (Q)
Elevated Temperature Cure Cycle	None	N/A
Room Temperature Cure	1 week***	N/A (Q)
Working Life	0.25 hour	N/A (Q)
Shelf Life, unopened	6 months @ 25°C (77°F)	N/A (Q)
Minimum thickness recommended	0.010 in (0.25 mm)	N/A
Maximum thickness recommended	0.125 in (3.18 mm)	N/A
Volatile Organic Content (VOC)	0 g/l	Calculated
Theoretical Coverage Area at 0.010" Thick per Pound (454 grams)	1375 in ² (8871 cm ²)	N/A
Theoretical Coverage - Length of an 1/8" Diameter Bead per Pound (454 grams)	90 feet (27.4 m)	N/A

Notes: N/A – Not Applicable, (Q/C) - Qualification and Conformance Test, (Q) - Qualification Test

* This test Method is available from Parker Chomerics.

** Minimum values listed are based on using the CHO-SHIELD 1086 primer that typically comes bundled with the CHO-BOND.

*** Cure is sufficient for handling in 24 hours. Full specification properties are developed after 1 week (168 hours) at room temperature.

Table 2 Ordering Information

Product	Weight (grams)	Packaging	Part Number	Primer Included
CHO-BOND 1075	71	1.5 fluid ounce foil tube	50-02-1075-0000	1086
	71	1.5 fluid ounce foil tube	50-02-1075-1000	No
	284	6 fluid ounce SEMCO cartridge	50-01-1075-0000	1086

Table 3 Primer Ordering Information

Product	Weight (grams)	Packaging	Part Number
CHO-BOND 1086	10	3 gram glass vial	50-10-1086-0000
	95	4 fluid ounce glass bottle	50-04-1086-0000
	375	1 pint can	50-01-1086-0000

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.

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